

# PATENT ASSIGNMENT

Electronic Version v1.1

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
Byung Gyun Bae	11/24/2009
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	TaeguTec, Ltd.
<b>Street Address:</b>	304 Yonggye-ri, Gachang-myeon
<b>Internal Address:</b>	Dalseong-gun
<b>City:</b>	Daegu
<b>State/Country:</b>	REPUBLIC OF KOREA
<b>Postal Code:</b>	711865
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	12664134
<b>CORRESPONDENCE DATA</b>	
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<b>ATTORNEY DOCKET NUMBER:</b>	T146 1080 US
<b>NAME OF SUBMITTER:</b>	Nanda K. Alapati
<b>Total Attachments: 2</b> source=T146_1080_US_Assignment#page1.tif source=T146_1080_US_Assignment#page2.tif	

CH \$40.00 12664134

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**PATENT**  
**REEL: 023641 FRAME: 0270**

# ASSIGNMENT

WHEREAS, as a below named inventor, I, ASSIGNOR, am an inventor of the invention entitled:

DEVICE AND METHOD FOR MANUFACTURING ENDMILL

which:

- ☐ is attached hereto;
- ☐ is identified as WCSR Docket No. \_\_\_\_\_;
- ☐ was filed on \_\_\_\_\_ as United States Application Serial No. \_\_\_\_\_.
- ☒ was filed on June 11, 2007 as PCT International Application No. PCT/KR2007/002807 and designated the United States.

WHEREAS, TAEGUTECH LTD., having a business address at 304 Yonggye-ri, Gachang-myeon, Dalseong-gun, Daegu 711-865, Republic of Korea, ASSIGNEE, is desirous of obtaining the entire right, title and interest in, to and under the said invention and said application in the United States;

NOW, THEREFORE, in consideration of good and valuable consideration, I, ASSIGNOR, have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the ASSIGNEE, its successors, legal representatives and assigns, for the territory of the United States of America, and not elsewhere, the entire right, title and interest in, to and under said United States application and said invention as fully set forth and described therein, and all divisions, renewals and continuations thereof, and all Patents of the United States which may be granted thereon and all reissues, reexamination certificates and extensions thereof; together with the right to file said application in the United States and the right to claim for the same the priority rights derived from any earlier filed application under the Patent Laws of the United States, the International Convention for the Protection of Industrial Property or any other international agreement, as may be applicable;

AND I, ASSIGNOR, HEREBY authorize and request the Commissioner of Patents and Trademarks of the United States to issue said application to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

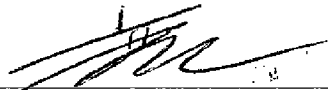
AND I, ASSIGNOR, HEREBY covenant and agree that I have full right to convey the entire interest herein assigned, and that I have not executed, and will not execute, any agreement in conflict herewith.

AND I, ASSIGNOR, HEREBY further covenant and agree that I will communicate to the said ASSIGNEE, its successors, legal representatives and assigns, any facts known to me respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing, reissue and applications and reexamination papers, make all rightful oaths, and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper protection for said invention in the United States.

of good and  
value

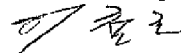
IN WITNESS WHEREOF, the undersigned inventor has affixed his signature.

1.

  
\_\_\_\_\_  
Inventor Name: BAE, Byung Gyun  
Residence Address: c/o TaeguTec Ltd, 304 Yonggye-ri, Gachang-myeon, Dalseong-gun, Daegu 711-865, Republic of Korea  
Country of Citizenship: Republic of Korea

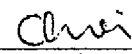
November 24, 2009

Date

  
\_\_\_\_\_  
Witness Lee, Chul Ho

November 24, 2009

Date

  
\_\_\_\_\_  
Witness Choi, Kye Pil

November 24, 2009

Date